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a bond layer comprising an elastomeric material interposed between said interconnecting medium lower surface and said package base upper surface, said package base being adapted for receiving said interconnecting medium.

31. The apparatus of claim 30, wherein the compliant bump probe tips are comprised of a solid material.

REMARKS

Claim 1 has been amended by substantially adding the subject matter of claim 5 thereto, claims 5 to 8 have been cancelled without prejudice, claim 9 has been cosmetically amended, claims 17 to 21 which were withdrawn from consideration have been cancelled and claims 22 to 31 have been added. Accordingly, claims 1 to 4, 9 to 16 and 22 to 31 are now active in this application. Claims 22 to 31 are substantially identical in claimed subject matter to claims 1 to 8, 10 and 11 of Patent No. 6,028,437 for purposes of having an interference declared. Please charge any costs to Deposit Account No. 20-0668.

With reference to the Office action, the election to prosecute the invention set forth in claims 1 to 16 is hereby affirmed without traverse.

With reference to the drawings, the compliant bump is shown in Fig. 3 and the complete package including the bump which is not specifically shown in Fig. 1 is otherwise shown in Fig. 1. Therefore, the combination of Figs. 1 and 3 provide the complete combination.

The rejection of claims 1 and 3 as being anticipated by Farnsworth et al. under 35 U.S.C. 102(b) is now moot in view of the amendment to claim 1.

The rejection of claims 2, 4, 6 and 8 under 35 U.S.C. 103(a) as being unpatentable over Farnsworth in view of Johnson and Potter is no longer in order at least in view of the predating of Potter.

The rejection of claims 5, 7 and 9 to 16 under 35 U.S.C. 103(a) as being unpatentable over Farnsworth in view of Potter is no longer in order at least in view of the predating of Potter.

All of the claims remaining in this application are believed to be readable on the Potter patent.

Claim 22 above is the same as claim 1 of Potter except that the terms used in the subject application "interconnecting medium" have been used in place of the term --probe membrane-- and "medium surface" has been used in place of the term --probe membrane head--. This readability should be sufficient to provide a first count (claim 9 above can also be used as a count) for purposes of interference with all other claims coming under the count or counts. Claim 22, which is essentially the same as claim 1 of Potter, is therefore readable on the subject disclosure as follows with the bracketed words being those used in Potter:

An apparatus adaptable for the testing of semiconductor devices comprising:

a package (10 of Fig. 1); and

an interconnecting medium (140) [probe membrane] contained within said package having electrical paths (171-173) adaptable for coupling to test circuitry, wherein said interconnecting medium [probe membrane] includes a medium surface (top surface of 140 in Fig. 1b) [probe membrane head], a plurality of standoffs (13 of Fig. 3) affixed to said medium surface [probe membrane], and a plurality of probe tips ((11 of

Fig. 3) affixed to said medium surface [probe membrane head], said probe tips adaptable for making electrical contact with pads on said semiconductor device, wherein said probe tips are compliant bump probe tips.

Claim 9 is readable on Potter as follows:

9. An interconnecting layer for use in a semiconductor package which comprises;

(a) an electrically insulating layer (121 of Potter);

(b) electrically conductive paths on said layer (traces not shown but discussed at column 3, lines 45 to 57), each of said paths having first and second spaced apart regions thereon, said second spaced apart region of each of said paths having a compliant bump (122) having a height greater than all other structures on said layer; and

(c) a standoff (123) disposed on said layer and having a height above said layer and less than said bump.

In view of the above and the attached Declaration, reconsideration and institution of an interference are respectfully requested. Further declarations from the inventors, if located, will be filed as they are received.

Respectfully submitted,



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